

## PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE: NEW ASSIGNMENT

NATURE OF CONVEYANCE: ASSIGNMENT

## CONVEYING PARTY DATA

Name	Execution Date
Masamoto Tanaka	10/10/2007
Tsutomu Sasaki	10/10/2007
Takayuki Kobayashi	10/10/2007
Kazuto Kawakami	10/10/2007
Masayoshi Fujishima	10/01/2007

## RECEIVING PARTY DATA

Name:	NIPPON STEEL MATERIALS CO., LTD.
Street Address:	14-1, Sotokanda 4-chome, Chiyoda-ku
City:	Tokyo
State/Country:	JAPAN
Postal Code:	101-0021

Name:	NIPPON MICROMETAL CORPORATION
Street Address:	158-1, Oaza Sayamagahara, Iruma-shi
City:	Saitama
State/Country:	JAPAN
Postal Code:	358-0032

## PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12281430

## CORRESPONDENCE DATA

Fax Number: (212)527-7701

*Correspondence will be sent via US Mail when the fax attempt is unsuccessful.*

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Correspondent Name: Joseph R. Robinson

OP \$40.00 12281430

500636450

PATENT  
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ATTORNEY DOCKET NUMBER:	09864/0210276-US0
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NAME OF SUBMITTER:	Kenneth Ma
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Total Attachments: 2 source=ASSIGN#page1.tif source=ASSIGN#page2.tif
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## ASSIGNMENT

For value received, I /we Masamoto TANAKA, Tsutomu SASAKI,  
Takayuki KOBAYASHI, Kazuto KAWAKAMI and Masayoshi FUJISHIMA  
residing respectively at Chiba, Japan; Chiba, Japan; Chiba, Japan; Chiba, Japan;  
Saitama, Japan  
hereby sell, assign, and transfer to NIPPON STEEL MATERIALS CO., LTD.;  
NIPPON MICROMETAL CORPORATION  
corporations existing under the laws of Japan  
located at 6-3, Otemachi 2-chome, Chiyoda-ku, Tokyo 1008071, Japan; 158-1 Oaza  
Sayamagahara, Iruma-shi, Saitama 3580032, Japan  
and its successors, assigns, and legal representatives, the entire right, title, and interest for  
all countries including the United States of America, in and to certain inventions relating to  
LEAD-FREE SOLDER ALLOY, SOLDER BALL AND ELECTRONIC MEMBER, AND LEAD-FREE SOLDER ALLOY,  
SOLDER BALL AND ELECTRONIC MEMBER FOR AUTOMOBILE-MOUNTED ELECTRONIC MEMBER  
described in an application for Letters Patent of the United States, executed by me/us on this  
date, and all patents which may be granted therefor, and all divisions, reissues, continuations  
and extensions thereof, and authorize and request the Commissioner of Patents and  
Trademarks to issue all patents on said improvements or resulting therefrom to said  
Company as assignee of the entire interest, and covenant that I/we have full right so to do,  
and agree that I/we will communicate to said Company or its representatives any facts  
known to me/us respecting said improvements and testify in any legal proceedings, sign all  
lawful papers, execute all divisional, continuing and reissue applications, make all rightful  
oaths and generally do everything possible to aid said Company, its successors, assigns, and  
nominees, to obtain and enforce proper protection for said invention in the United States.

Signature \_\_\_\_\_  
Masamoto TANAKA

Date \_\_\_\_\_

Signature \_\_\_\_\_  
Tsutomu SASAKI

Date \_\_\_\_\_

Signature \_\_\_\_\_  
Takayuki KOBAYASHI

Date \_\_\_\_\_

Signature \_\_\_\_\_  
Kazuto KAWAKAMI

Date \_\_\_\_\_

Signature M. Fujishima  
Masayoshi FUJISHIMA

Date Oct. 01. 2007


Signature \_\_\_\_\_

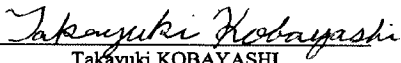
Date \_\_\_\_\_

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Trademarks to issue all patents on said improvements or resulting therefrom to said  
Company as assignee of the entire interest, and covenant that I/we have full right so to do,  
and agree that I/we will communicate to said Company or its representatives any facts  
known to me/us respecting said improvements and testify in any legal proceedings, sign all  
lawful papers, execute all divisional, continuing and reissue applications, make all rightful  
oaths and generally do everything possible to aid said Company, its successors, assigns, and  
nominees, to obtain and enforce proper protection for said invention in the United States.

Signature  Date October 10, 2007  
Masamoto TANAKA

Signature  Date October 10, 2007  
Tsutomu SASAKI

Signature  Date October 10, 2007  
Takayuki KOBAYASHI

Signature  Date October 10, 2007  
Kazuto KAWAKAMI

Signature \_\_\_\_\_ Date \_\_\_\_\_  
Masayoshi FUJISHIMA

Signature \_\_\_\_\_ Date \_\_\_\_\_